23 September 2004

L Number Search Text Hits DB 6214193.pn. 6099702.pn. USPAT: 2003/04/25 US-PGPUB; 11:32 EPO; JPO; DERWENT 3950184.pn. 2 USPAT: 2003/04/25 US-PGPUB; 11:58 EPO; JPO; DERWENT 14 3950184.URPN. USPAT 2003/04/25 11:58 ("3141793" | "3656173" | "3950184" | "4451507" | 5 USPAT 2003/04/25 "5084483").PN. 12:01 17 ("3798056" | "3950184" | "4339319" | "4373988" | USPAT 2003/04/25 "4466864" | "4856456" | "5000827" | "5169408" | 13:58 "5312487" | "5340437" | "5472592" | "5670034" | "5677000" | "5893966" | "5930549" | "6077412" | "6099702").PN. 33 5000827.URPN. **USPAT** 2003/04/25 12:04 53 5169408.URPN. USPAT 2003/04/25 12:41 33 5000827.URPN. USPAT 2003/04/25 12:50 2247 204/212,225,237,275.1.ccls. USPAT; 2003/04/25 US-PGPUB; 13:58 EPO; JPO; DERWENT 773 204/224r.ccls. USPAT; 2003/04/25 US-PGPUB; 13:58 EPO; JPO; DERWENT 2837 204/212,225,237,275.1.ccls. 204/224r.ccls. USPAT; 2003/04/25 US-PGPUB; 14:00 EPO; JPO; DERWENT 2190 118/416,500,501.ccls. USPAT; 2003/04/25 US-PGPUB; 14:01 EPO; JPO; **DERWENT** 5015 (204/212,225,237,275.1.ccls. 204/224r.ccls.) USPAT; 2003/04/25 118/416,500,501.ccls. US-PGPUB; 14:01 EPO; JPO; **DERWENT** 1027 ((204/212,225,237,275.1.ccls. 204/224r.ccls.) USPAT; 2003/04/25 118/416,500,501.ccls.) and (semiconductor or wafer) US-PGPUB; 14:02 EPO; JPO; DERWENT 557 (((204/212,225,237,275.1.ccls. 204/224r.ccls.) USPAT; 2003/04/25 118/416,500,501.ccls.) and (semiconductor or wafer)) US-PGPUB; 14:02 and (spinning or spin or spun or rotate or rotated or EPO; JPO; rotating) DERWENT

		///004/040 005 007 0754   004/004	1	T
-	90	((((204/212,225,237,275.1.ccls. 204/224r.ccls.)	USPAT;	2003/04/25
		118/416,500,501.ccls.) and (semiconductor or wafer))	US-PGPUB;	14:36
		and (spinning or spin or spun or rotate or rotated or	EPO; JPO;	
		rotating)) and (recycle or recycling or recylcer or	DERWENT	
		reclaim or reclamation or recycled or reclaimed or		
	_	recover or recovered or recovery or recovering)		
-	3	("5922138"   "6168691"   "6187152").PN.	USPAT	2003/04/25
	_			14:29
-	0	6352623.URPN.	USPAT	2003/04/25
				14:33
-	3776	205/122,123,157,220.ccls. 427/98,299,352.ccls.	USPAT;	2003/04/25
			US-PGPUB;	14:34
			EPO; JPO;	
			DERWENT	
-	940	(205/122,123,157,220.ccls. 427/98,299,352.ccls.)	USPAT;	2003/04/25
		and (semiconductor or wafer)	US-PGPUB;	14:34
			EPO; JPO;	
			DERWENT	
-	504	((205/122,123,157,220.ccls. 427/98,299,352.ccls.)	USPAT;	2003/04/25
		and (semiconductor or wafer)) and (cleaning or clean	US-PGPUB;	14:35
1		or cleaned or rinsed or rinse or rinsing or wash or	EPO; JPO;	
		washing or washed)	DERWENT	
-	53	(((205/122,123,157,220.ccls. 427/98,299,352.ccls.)	USPAT;	2003/04/25
		and (semiconductor or wafer)) and (cleaning or clean	US-PGPUB;	14:36
		or cleaned or rinsed or rinse or rinsing or wash or	EPO; JPO;	
		washing or washed)) and (recycle or recycling or	DERWENT	
		recylcer or reclaim or reclamation or recycled or		
		reclaimed or recover or recovered or recovery or		
		recovering)		
-	90	((((204/212,225,237,275.1.ccls. 204/224r.ccls.)	USPAT;	2003/04/25
		118/416,500,501.ccls.) and (semiconductor or wafer))	US-PGPUB;	15:01
		and (spinning or spin or spun or rotate or rotated or	EPO; JPO;	
		rotating)) and (recycle or recycling or recycler or	DERWENT	
	ļ ļ	reclaim or reclamation or recycled or reclaimed or		
		recover or recovered or recovery or recovering)		
-	53	(((205/122,123,157,220.ccls. 427/98,299,352.ccls.)	USPAT;	2003/04/25
		and (semiconductor or wafer)) and (cleaning or clean	US-PGPUB;	14:37
		or cleaned or rinsed or rinse or rinsing or wash or	EPO; JPO;	
		washing or washed)) and (recycle or recycling or	DERWENT	
		recycler or reclaim or reclamation or recycled or		
		reclaimed or recover or recovered or recovery or	'	
		recovering)		
-	225	(((205/122,123,157,220.ccls. 427/98,299,352.ccls.)	USPAT;	2003/04/25
		and (semiconductor or wafer)) and (cleaning or clean	US-PGPUB;	14:37
		or cleaned or rinsed or rinse or rinsing or wash or	EPO; JPO;	
		washing or washed)) and (spin or spinning or spun or	DERWENT	
		rotate or rotating or rotated or revolve or revolved or		
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	l	revolving)		i

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-	40	((((205/122,123,157,220.ccls. 427/98,299,352.ccls.)	USPAT;	2003/04/25
		and (semiconductor or wafer)) and (cleaning or clean	US-PGPUB;	14:37
		or cleaned or rinsed or rinse or rinsing or wash or	EPO; JPO;	
		washing or washed)) and (spin or spinning or spun or	DERWENT	
	ļ	rotate or rotating or rotated or revolve or revolved or		
		revolving)) and (recycle or recycling or recycler or		
		reclaim or reclamation or recycled or reclaimed or		
		recover or recovered or recovery or recovering)		
<del>-</del>	11	(US-6099702-\$ or US-6214193-\$ or US-5677000-\$	USPAT;	2003/06/10
		or US-3950184-\$ or US-6551487-\$ or	US-PGPUB;	11:50
		US-6299751-\$).did.	EPO; JPO;	
			DERWENT	
-	1	2000wo-us28210.ap,prai.	USPAT;	2003/06/10
			US-PGPUB;	11:53
			EPO; JPO;	
			DERWENT	
-	16	6099702.URPN.	USPAT	2003/06/10 11:51
-	15	("3798056"   "3950184"   "4339319"   "4373988"	USPAT	2003/06/10 11:51
		"4466864"   "4856456"   "5000827"   "5169408"		
		"5312487"   "5340437"   "5472592"   "5670034"		
		"5677000"   "5893966"   "5930549").PN.		
-	0	6214193.URPN.	USPAT	2003/06/10 11:51
-	17	("3798056"   "3950184"   "4339319"   "4373988"	USPAT	2003/06/10 11:51
		"4466864"   "4856456"   "5000827"   "5169408"		
		"5312487"   "5340437"   "5472592"   "5670034"		
		"5677000"   "5893966"   "5930549"   "6077412"		
		"6099702").PN.		*
_	33	6099702.URPN. (("3798056"   "3950184"	USPAT;	2003/06/10 11:51
		"4339319"   "4373988"   "4466864"   "4856456"	US-PGPUB;	2005/00/10 11:51
	-	"5000827"   "5169408"   "5312487"   "5340437"	EPO; JPO;	
		"5472592"   "5670034"   "5677000"   "5893966"	DERWENT	
		"5930549").PN.) 6214193.URPN. (("3798056"	OCKWC/41	
		"3950184"   "4339319"   "4373988"   "4466864"		
		"4856456"   "5000827"   "5169408"   "5312487"		
		"5340437"   "5472592"   "5670034"   "5677000"		
		"5893966"   "5930549"   "6077412"		
		"6099702").PN.)		
_	1	2001-580725.NRAN.	DERWENT	2003/06/10
			DEKWENI	11:52
_	12	(("6139703") or ("6080291") or ("5932077") or	USPAT;	
	"	("5447615") or ("5421987") or ("5344491")).PN.	US-PGPUB;	2003/06/10
		( ) (	EPO; JPO;	12:29
			DERWENT;	
_	1	836844.apn.	IBM_TDB	2002/07/40
		0000 14.upn.	USPAT;	2003/06/10
			US-PGPUB;	12:47
			EPO; JPO;	
			DERWENT;	
_	2401	204/100 212 222 242 275 1 207 04 207 04 207	IBM_TDB	
-	2401	204/199,212,232,263,275.1,297.01,297.06,297.07,297		2003/06/10
			US-PGPUB;	12:48
			EPO; JPO;	
			DERWENT;	
	<u> </u>		IBW_TDB	

	700	004/004	T ::	T
-	780	204/224r.ccls.	USPAT;	2003/06/10
			US-PGPUB;	12:48
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3033	204/199,212,232,263,275.1,297.01,297.06,297.07,297	.08 SERAST;	2003/06/10
		204/224r.ccls.	US-PGPUB;	12:48
-			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	73	(204/199,212,232,263,275.1,297.01,297.06,297.07,29		2003/06/10
		204/224r.ccls.) and ((multiple or plural\$3 or second)	US-PGPUB;	12:49
		near (outlet or withdraw\$3 or collect\$4))	EPO; JPO;	Th. Ty
		The content of withdraway of concerp ty	DERWENT;	
			IBM_TDB	
_	26	(204/199,212,232,263,275.1,297.01,297.06,297.07,29		2002/0//10
		204/224r.ccls.) and ((multiple or plural\$3) near	ľ	2003/06/10
		(outlet or withdraw\$3 or collect\$4))	US-PGPUB;	12:49
		(outlet or withdraws or collects4))	EPO; JPO;	
İ			DERWENT;	
	4-7	//004/400 040 000 040 077 4 007 04 077	IBW_TDB	
-	47	((204/199,212,232,263,275.1,297.01,297.06,297.07,29		2003/06/10
		204/224r.ccls.) and ((multiple or plural\$3 or second)	US-PGPUB;	12:52
	1	near (outlet or withdraw\$3 or collect\$4))) not	EPO; JPO;	
		((204/199,212,232,263,275.1,297.01,297.06,297.07,29	700BRAMENT;	
	]	204/224r.ccls.) and ((multiple or plural\$3) near	IBM_TDB	
		(outlet or withdraw\$3 or collect\$4)))		
-	16	(204/199,212,232,263,275.1,297.01,297.06,297.07,297	.085PA(3.;	2003/06/10
		204/224r.ccls.) and (situ near (rins\$3 or process\$3	US-PGPUB;	12:56
	Ì	or clean\$3 or wash\$3))	EPO; JPO;	
	]		DERWENT;	
			IBM_TDB	
_	2	5932077.pn.	USPAT;	2004/01/07
		•	US-PGPUB;	14:58
			EPO; JPO;	155
			DERWENT;	
•	·		IBM_TDB	
-	25	5932077.URPN.	USPAT	2004/01/07
			JULAT	14:58
-	64	204/198,199.ccls. and (microelectronic or wafer or	USPAT;	1
[		semiconductor)	· ·	2004/01/07
		constant of j	US-PGPUB;	15:12
1			EPO; JPO;	
		,	DERWENT;	
	4.0	204/108/100 and and 6 to 1 to 1	IBM_TDB	
-	18	204/198,199.ccls. and (microelectronic or wafer or	USPAT;	2004/01/07
		semiconductor) and (spray\$4)	US-PGPUB;	15:12
			EPO; JPO;	
			DERWENT;	
			IBW_LDB	
-	2342	204/212,225,237,275.1.ccls.	USPAT;	2004/01/08
	ſ		US-PGPUB;	09:18
			EPO; JPO;	
			DERWENT	

	011	204/224:	T	T
-	811	204/224r.ccls.	USPAT;	2004/01/08
			US-PGPUB;	09:18
			EPO; JPO;	
		004/040 007 007 077 4	DERWENT	· ·
-	2957	204/212,225,237,275.1.ccls. 204/224r.ccls.	USPAT;	2004/01/08
			US-PGPUB;	09:18
			EPO; JPO;	
			DERWENT	
-	373	(204/212,225,237,275.1.ccls. 204/224r.ccls.) and	USPAT;	2004/01/08
		(wafer or semiconductor or microelectronic)	US-PGPUB;	09:19
			EPO; JPO;	
1			DERWENT	
-	8	((204/212,225,237,275.1.ccls. 204/224r.ccls.) and	USPAT;	2004/01/08
		(wafer or semiconductor or microelectronic)) and	U5-PGPUB;	09:19
		(tilt\$5 and spray\$5)	EPO; JPO;	
			DERWENT	
-	14	((204/212,225,237,275.1.ccls. 204/224r.ccls.) and	USPAT;	2004/01/08
		(wafer or semiconductor or microelectronic)) and	US-PGPUB;	10:12
		(tilt\$5 and (spray\$5 or nozzle))	EPO; JPO;	
	ĺ		DERWENT	
-	100	(204/198-227.ccls. and (microelectronic or wafer or	USPAT;	2004/01/08
		semiconductor)) and ((contact or electrode or	US-PGPUB;	11:48
		cathode) with (clean\$3 or wash\$3 or rins\$5))	EPO; JPO;	11. 10
		, , , , , , , , , , , , , , , , , , , ,	DERWENT	
	2	6156167.pn.	USPAT;	2004/01/08
		<b>, ,</b> , , , , , , , , , , , , , , , ,	US-PGPUB;	11:48
			EPO; JPO;	11.40
			DERWENT	
_	1	836844.apn.	USPAT;	2004/01/09
	_		US-PGPUB;	09:24
1			EPO; JPO;	09.24
			DERWENT:	
			IBM_TDB	
_	438	204/198-227.ccls. and (microelectronic or wafer or	USPAT;	2004/01/00
	.00	semiconductor)	US-PGPUB;	2004/01/09
		John Conductor y	EPO; JPO;	09:53
			DERWENT	
_	20	(204/198-227.ccls. and (microelectronic or wafer or	USPAT;	2004/01/00
		semiconductor)) and (tilt\$4 with (wafer or substrate	US-PGPUB;	2004/01/09
		or semiconductor or microelectronic))	EPO; JPO;	09:53
		1. 12. modification of fine rocice frome)	DERWENT	
_	5	6613214.pn. 6258220.pn.	USPAT;	2004/01/09
1		озода при одобедо.рг.	US-PGPUB;	1
			EPO; JPO;	09:44
[			DERWENT	
_	3	6251236.pn. 6258220.pn.	USPAT;	2004/01/00
	٦	0-01-00.pm 0-00220.pm.		2004/01/09
ĺ			US-PGPUB;	09:44
			EPO; JPO;	
_	11422	(205/\$ ccls on 204/\$ cols ) and (misses leasthernis and	DERWENT	000440455
	11766	(205/\$.ccls. or 204/\$.ccls.) and (microelectronic or wafer or semiconductor)	USPAT;	2004/01/09
	ļ	water or semiconductor)	US-PGPUB;	09:53
	į		EPO; JPO;	
			DERWENT	

- 121 ((205/\$.ccls. or 204/\$.ccls.) and (microelectronic or wafer or semiconductor)) and (tilt\$4 with (wafer or	USPAT; US-PGPUB;	2004/01/09
	US-PGPUB;	00 = 4
		09:54
substrate or semiconductor or microelectronic))	EPO; JPO;	
	DERWENT	
- 101 (((205/\$.ccls. or 204/\$.ccls.) and (microelectronic or	USPAT;	2004/01/09
wafer or semiconductor)) and (tilt\$4 with (wafer or	US-PGPUB;	09:54
substrate or semiconductor or microelectronic))) not	EPO; JPO;	
((204/198-227.ccls. and (microelectronic or wafer or	DERWENT	
semiconductor)) and (tilt\$4 with (wafer or substrate	DERTICIAL	
or semiconductor or microelectronic)))		
- 1554 422/292,300.ccls.	LICDAT.	2004/00/22
1554 422/272,300.0015.	USPAT;	2004/09/23
	US-PGPUB;	10:54
	EPO; JPO;	
	DERWENT;	
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- 16 422/292,300.ccls. and (wafer or microelectronic)	USPAT;	2004/09/23
	US-PGPUB;	10:54
	EPO; JPO;	
	DERWENT;	
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1 1 4444 144 44 44 44 44	USPAT;	2004/09/23
	US-PGPUB;	10:55
l ' ' '	EPO; JPO;	
	DERWENT;	
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1	USPAT;	2004/09/23
	US-PGPUB;	10:55
	EPO; JPO;	10.55
	DERWENT;	
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	USPAT;	2004/00/22
		2004/09/23
	US-PGPUB;	10:55
	EPO; JPO;	
	DERWENT;	
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	USPAT;	2004/09/23
	US-PGPUB;	10:55
	EPO; JPO;	
	DERWENT;	
	IBM_TDB	
	USPAT;	2004/09/23
	US-PGPUB;	10:56
(chemical or fluid)) and (chamber or container)	EPO; JPO;	
	DERWENT;	
	IBM_TDB	
	USPAT;	2004/09/23
	US-PGPUB;	10:56
	EPO; JPO;	
	DERWENT;	
	IBM_TDB	

-	452	134/58r,94.1,95.1,95.2,95.3,103.2,198.ccls. and	USPAT;	2004/09/23
		(wafer or microelectronic)	US-PGPUB:	10:56
			EPO; JPO;	
			DERWENT:	
			IBM_TDB	
-	320	(134/58r,94.1,95.1,95.2,95.3,103.2,198.ccls. and	USPAT;	2004/09/23
		(wafer or microelectronic)) and (clean\$3 or rins\$3)	US-PGPUB;	10:56
ľ		near3 (wafer or microelectronic)	EPO; JPO;	
}			DERWENT;	
			IBM_TDB	
-	196	((134/58r,94.1,95.1,95.2,95.3,103.2,198.ccls. and	USPAT;	2004/09/23
		(wafer or microelectronic)) and (clean\$3 or rins\$3)	US-PGPUB;	10:57
		near3 (wafer or microelectronic)) and (spray or	EPO; JPO;	
		stream)	DERWENT;	*
	132	////124/58, 044 054 05 0 05 2 402 0 400	IBM_TDB	
-	132	(((((134/58r,94.1,95.1,95.2,95.3,103.2,198.ccls. and	USPAT;	2004/09/23
		(wafer or microelectronic)) and (clean\$3 or rins\$3)	US-PGPUB;	10:57
		near3 (wafer or microelectronic)) and (spray or stream)) and (chemical or fluid)) and (chamber or	EPO; JPO;	
		container)) and (rais\$3 or lower\$3 or vertical\$4)	DERWENT;	
_	2	6050275.pn.	IBM_TDB	2004/00/02
	-	ооостори.	USPAT; US-PGPUB;	2004/09/23
			EPO; JPO;	10:57
			DERWENT;	
			IBM_TDB	